

## AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application.

1. – 51. (Cancelled).

52. (currently amended) A non-volatile memory system, comprising:

a card ~~having a bottom surface, a top surface, a front surface, a rear surface and two side surfaces, said card includes having a set of contacts on an external said bottom surface, of said card, said card having a first surface and a second surface on an opposite side of said card from said first surface, said first~~ said top surface having a raised portion, one of said side surfaces includes a notch portion and an angle portion;

a circuit board ~~enclosed within in~~ in said card;

a plurality of non-volatile storage elements enclosed within said card and connected to said circuit board; and

passive electrical elements enclosed within said card and connected to said circuit board, said passive electrical elements are positioned in a part of said card at least partially defined by said raised portion.

53. (Previously presented) A non-volatile memory system according to claim 52, wherein:

said non-volatile storage elements are flash memory cells.

54. (cancelled)

55. (Previously presented) A non-volatile memory system according to claim 52, further comprising:

a controller element enclosed within said card and connected to said circuit board.

56. (Previously presented) A non-volatile memory system according to claim 55, wherein:

said passive electrical elements are in communication with said controller.

57. (cancelled)

58. (Previously presented) A non-volatile memory system according to claim 52, wherein:

said passive electrical elements are capacitors.

59. (cancelled)

60. (Previously presented) A non-volatile memory system according to claim 52, wherein:

said raised portion provides a grip to grab said card.

61. (currently amended) A non-volatile memory system according to claim 52, wherein:

said card includes molding material, said molding material defines said top surface and said one of said side surfaces, ~~encapsulating said circuit board, said non-volatile storage elements and said passive electrical elements.~~

62. (Previously presented) A non-volatile memory system according to claim 52, wherein:

said non-volatile storage elements are flash memory devices in a flash memory array; and  
said passive electrical elements are capacitors.

63. (currently amended) A non-volatile memory system, comprising:  
a card having a first dimension and a second dimension, said card has a first thickness along a first portion of said first dimension ~~dimensions~~ and a second thickness along a second

portion of said first dimension, said second thickness is greater than said first thickness, said card having a side surface, said side surface includes a notch portion and an angled portion;

a plurality of non-volatile storage elements enclosed within said card; and  
passive electrical elements enclosed within said card, said passive electrical elements are positioned in said second portion.

64. (Previously presented) A non-volatile memory system according to claim 63, wherein:

said passive electrical elements are capacitors.

65. (Previously presented) A non-volatile memory system according to claim 64, wherein:

said first dimension is length;  
said second dimension is width; and  
said non-volatile storage elements are flash memory devices.

66. (Previously presented) A non-volatile memory system according to claim 63, wherein:

said first dimension is length; and  
said second dimension is width.

67. (Previously presented) A non-volatile memory system according to claim 63, wherein:

said passive electrical elements are in electrical communication with said non-volatile storage elements.

68. (Previously presented) A non-volatile memory system according to claim 63, further comprising:

a circuit board, said non-volatile storage elements and said passive electrical elements are connected to said circuit board.

69. (Previously presented) A non-volatile memory system according to claim 68, further comprising:

a controller, said controller is positioned within said card and is in communication with said non-volatile storage elements; and

a set of electrical contacts on an external surface of said card, said set of electrical contacts are in communication with said controller.

70. (Previously presented) A non-volatile memory system according to claim 63, wherein:

said non-volatile storage elements are flash memory devices.

71. (Previously presented) A non-volatile memory system according to claim 63, further comprising:

a controller element enclosed within said card and in communication with said non-volatile storage elements.

72. (currently amended) A non-volatile memory system according to claim 63, wherein:

said card having a top first surface and a ~~second~~ bottom surface on an opposite side of said card from said top first surface, said top first surface having a raised portion, said raised portion defines said second thickness.

73. (currently amended) A non-volatile memory system according to claim 72, ~~63~~, wherein:

said card includes molding material encapsulating said plurality of non-volatile storage elements and said passive electrical elements, said molding material defines said top surface and said side surface.

74. – 79. (Cancelled)

80. (currently amended) A non-volatile memory system, comprising:

a removable peripheral card having a first dimension and a second dimension, said removable peripheral card has a first thickness along a first portion of said first dimension dimensions and a second thickness along a second portion of said first dimension, said second thickness is greater than said first thickness, said removable peripheral card having a side surface, said side surface includes a notch portion;

non-volatile storage elements enclosed within said peripheral card; and

a passive electrical component enclosed within said removable peripheral card, said passive electrical element is positioned in said second portion.

81. (Cancelled)

82. (new) A non-volatile memory system, comprising:

a circuit board;

a passive electrical component connected to said circuit board;

a flash memory chip connected to said circuit board;

molding material forming a peripheral card having a top surface, a front surface, a rear surface and two side surfaces, one of said side surfaces has an angle portion and a notch portion, said top surface having a raised portion adjacent said rear surface, said peripheral card having a first section and a second section, said second section is thicker than said first section to accommodate said passive electrical component, said circuit board and said flash memory chip are positioned in said molding material.

83. (new) A non-volatile memory system, comprising:

a card having a bottom surface, a top surface, a front surface, a rear surface and two side surfaces, said card includes a set of contacts on said bottom surface, said top surface having a raised portion, one of said side surfaces includes an angle portion;

a circuit board in said card;

a plurality of non-volatile storage elements enclosed within said card and connected to said circuit board; and

a passive electrical element enclosed within said card and connected to said circuit board, said passive electrical elements is positioned in a part of said card at least partially defined by said raised portion.

84. (new) A non-volatile memory system according to claim 83, wherein:

said card comprises molding material forming said top surface and said one of said side surfaces, said molding material defines said raised portion and said angle portion.

85. (new) A non-volatile memory system according to claim 83, wherein:

said card comprises molding material forming said top surface and said side surfaces, said molding material does not form said bottom surface, said circuit board defines said bottom surface.

86. (new) A non-volatile memory system according to claim 80, wherein:

said card comprises molding material, said molding material defines said notch portion, said first thickness and said second thickness.